

Thermally conductive products

Thermipad® TP 22828

Heat conducting pad

Composition: Thermipad® TP 22828 has a low molecular weight siloxane content. This makes it less likely that contact faults will occur.

Properties: Thermipad® TP 22828 has excellent thermal conductivity and flexibility, rapid heat dissipation and heat transfer to parts. Thermipad® TP 22826 is an elastic, optimally mouldable and low-stress gap filler.

Applications: Thermipad® TP 22828 is used, for example, for the thermal connection of electronic components, semiconductors, ICs, transistors and heat distributors to heat sinks.

Standard colour: Thermipad® TP 22828 is supplied in the color black.

Delivery forms: Thermipad® TP 22828 is supplied in the form of 400 x 200 mm sheets. Cuts and shapes according to customer specifications possible.

Storage conditions: Thermipad® TP 22828 should be stored in dry rooms at room temperature and in its original packaging.

Dr. Dietrich Müller GmbH

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Properties	Method	Unit	Value
Total thickness	-	mm	0,5 – 2,0
Thermal conductivity	ASTM-D5470	W/mK	10
Hardness	ASKER C	-	< 65
Temperature range	-	°C	- 40 to + 150

Trademark Information: Thermiflex® is a registered trademark of the company Dr. Dietrich Müller GmbH, Germany

Please note:

The information in this data sheet is based on our current knowledge and experience. They do not disengage the fabricator and user from own tests and inspections because of the plenty of possible effects. There is no judicial binding assurance of certain properties or of the qualification for a concrete application in our declaration. We recommend consulting us in individual cases. The acceptor of our products has to observe possible industrial property rights as well as present laws by himself.

Dr. Dietrich Müller GmbH